

AMENDMENT TO THE CLAIMS:

1. (Currently amended) A pattern formation material for electron beam lithography, comprising an alkali-soluble resin and a photoacid generator which generates an acid when irradiated with an electron beam, wherein

said pattern formation material further comprises first and second dissolution inhibiting groups each of which has a capacity of inhibiting dissolution of said alkali-soluble resin in an alkali solution and loses the capacity upon application of an acid, said first dissolution inhibiting group increasing a sensitivity of said pattern formation material when left to stand in a vacuum after being irradiated with an electron beam, and said second dissolution inhibiting group decreasing the sensitivity of said pattern formation material when left to stand in a vacuum after being irradiated with an electron beam, and

a ratio of said first dissolution inhibiting group to said second dissolution inhibiting group is adjusted such that a size of an alkali-soluble portion, which is a portion made soluble in said alkali solution when said pattern formation material is irradiated with an electron beam, is substantially held constant independently of a standing time in a vacuum.

2. (Original) A material according to claim 1, wherein at least one of said first and second dissolution inhibiting groups is a functional group which modifies said alkali-soluble resin.

3. (Original) A material according to claim 1, wherein said pattern formation material further comprises a dissolution inhibitor, and at least one of said first and second dissolution inhibiting groups is a functional group which forms said dissolution inhibitor.

4. (Original) A material according to claim 1, wherein said first dissolution inhibiting group is a t-butoxycarbonyloxy group.

5. (Original) A material according to claim 1, wherein said second dissolution inhibiting group is an acetal-type functional group.

6. (Currently amended) A pattern formation material according to claim 4 for electron beam lithography comprising an alkali-soluble resin and a photoacid generator which generates an acid when irradiated with an electron beam, wherein said pattern formation material further comprises first and second dissolution inhibiting groups each of which has a capacity of inhibiting dissolution of said alkali-soluble resin in an alkali solution and loses the capacity upon application of an acid said first dissolution inhibiting group increasing a sensitivity of said pattern formation material when left to stand in a vacuum after being irradiated with an electron beam, and said second dissolution inhibiting group decreasing the sensitivity of said pattern formation material when left to stand in a vacuum after being irradiated with an electron beam,

a ratio of said first dissolution inhibiting group to said second dissolution inhibiting group is adjusted such that a size of an alkali-soluble portion, which is a portion made

soluble in said alkali solution when said pattern formation material is irradiated with an electron beam, is substantially held constant independently of a standing time in a vacuum, and

the ratio of said first dissolution inhibiting group to said second dissolution inhibiting group is adjusted such that a difference between the size of said alkali-soluble portion immediately after being irradiated with an electron beam in a vacuum and the size of said alkali-soluble beam in a vacuum and the size of said alkali-soluble portion left to stand for 10 hr in a vacuum after being irradiated with an electron beam is not more than +/- 5 nm.

Claims 7 - 19 (Canceled)

20. (New) A material according to claim 6, wherein at least one of said first and second dissolution inhibiting groups is a functional group which modifies said alkali-soluble resin.

21. (New) A material according to claim 6, wherein said pattern formation material further comprises a dissolution inhibitor, and at least one of said first and second dissolution inhibiting groups is a functional group which forms said dissolution inhibitor.

22. (New) A material according to claim 6, wherein said first dissolution inhibiting group is a t-butoxycarbonyloxy group.

23. (New) A material according to claim 6, wherein said second dissolution inhibiting group is an acetal-type functional group.